

SOT1583-2

HUQFN20, plastic, thermal enhanced ultra thin quad flatpack; no leads; 20 terminals; 0.5 mm pitch; 4 mm x 3 mm x 0.65 mm body

8 August 2018

Package information

Package summary 1

Terminal position code Q (quad) HUQFN20 Package type descriptive code

HUQFN (thermal enhanced ultra thin quad Package style descriptive code

flatpack; no leads)

Package body material type P (plastic)

Mounting method type S (surface mount)

16-07-2018 Issue date

98ASA00041D Manufacturer package code

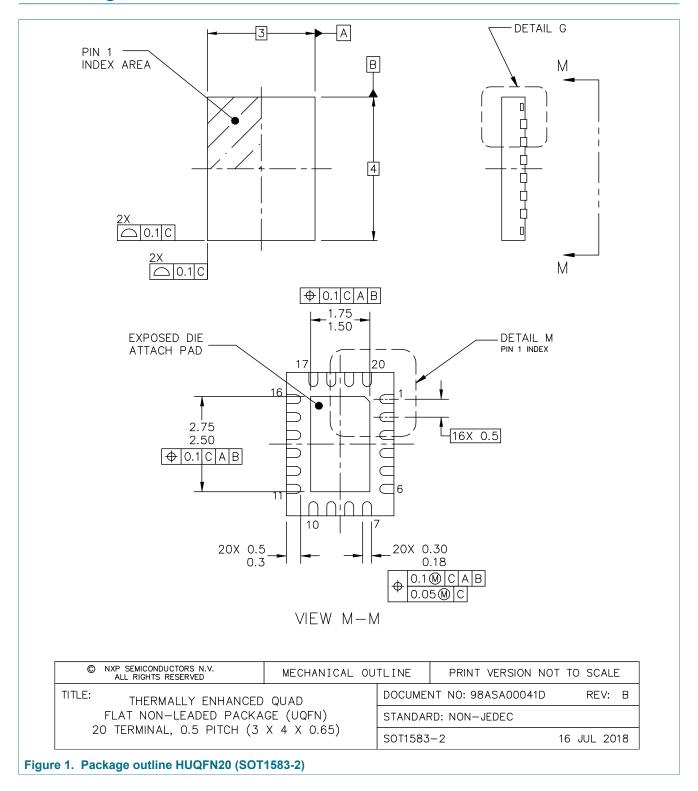
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	3	-	mm
package width	-	4	-	mm
package height	-	0.65	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	20	-	

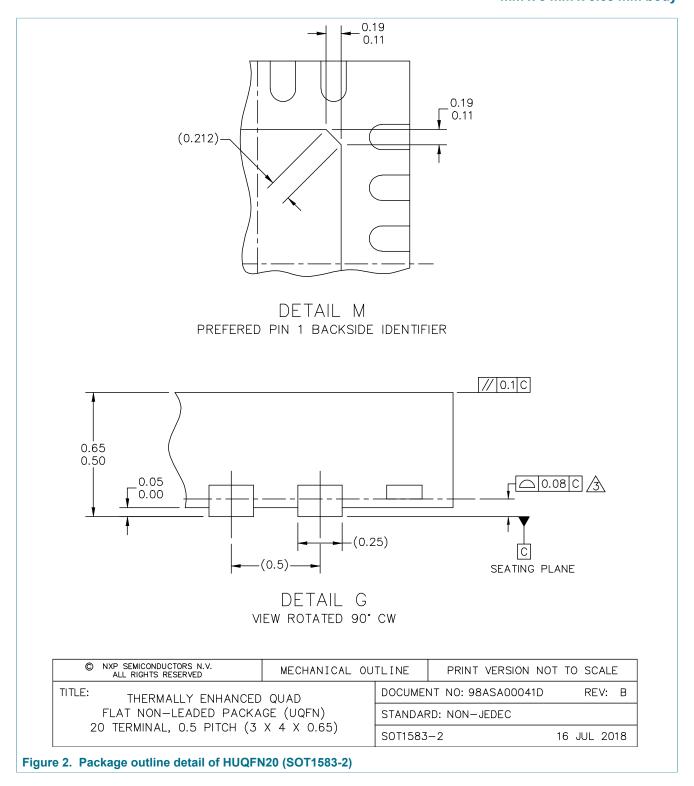


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2 Package outline



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NOTES:

- 1. DIMENSIONS ARE IN MILLIMETERS.
- 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.

3. COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.

4. MIN METAL GAP SHOULD BE 0.2MM.

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FLAT NON-LEADED PACKAGE (UQFN)		DOCUMEN	NT NO: 98ASA00041D	REV: B
		STANDARD: NON-JEDEC		
20 TERMINAL, 0.5 PITCH (3	(4 X 0.65)	SOT1583	-2	16 JUL 2018

Figure 3. Package outline note HUQFN20 (SOT1583-2)

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3 Legal information

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Contents

1	Package summary1
2	Package outline2
3	Legal information5